SEMICONDUCTOR ELECTRONIC COMPONENT AND SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT

The problem of the present invention is to provide a chip-on-chip type semiconductor electronic component and a semiconductor device which can meet the requirements for further density increase of semiconductor integrated circuits.

The present invention provides: a chip-on-chip type semiconductor electronic component in which a circuit surface of a first semiconductor chip and a circuit surface of a second semiconductor chip are opposed to each other, wherein the distance X between the first semiconductor chip and the second semiconductor chip is 50 μm or less, and the shortest distance Y between the side surface of the second semiconductor chip and the first external electrode is 1 mm or less; and a semiconductor device comprising the same.

FIGURE 1